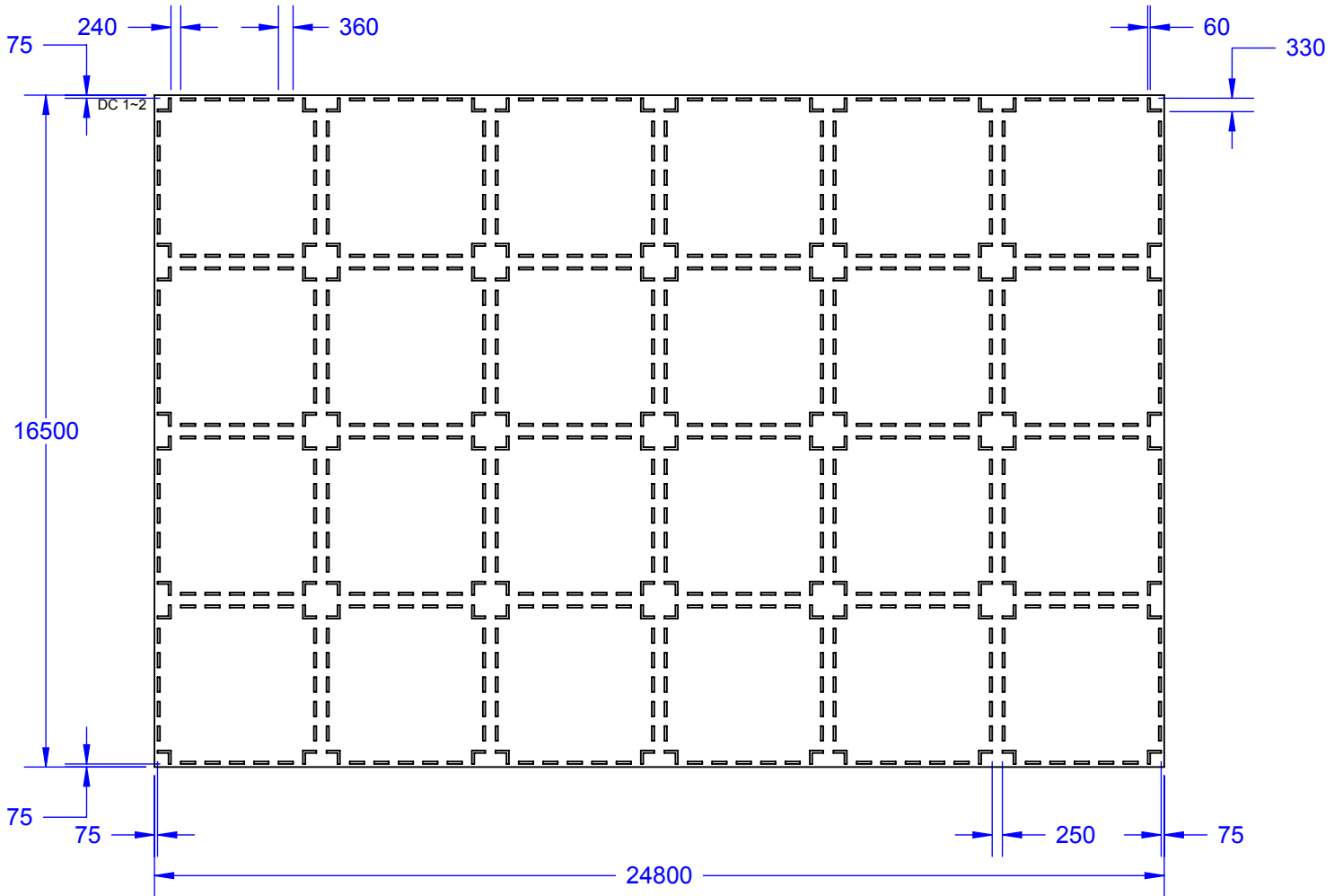


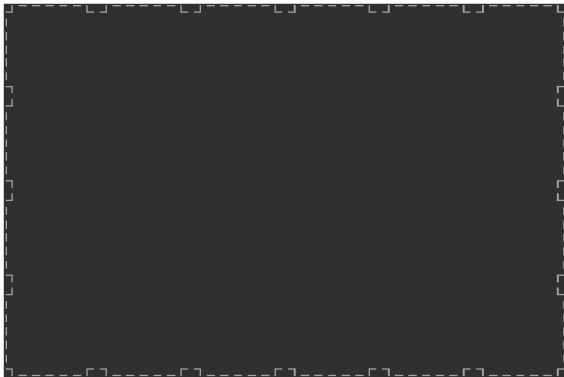
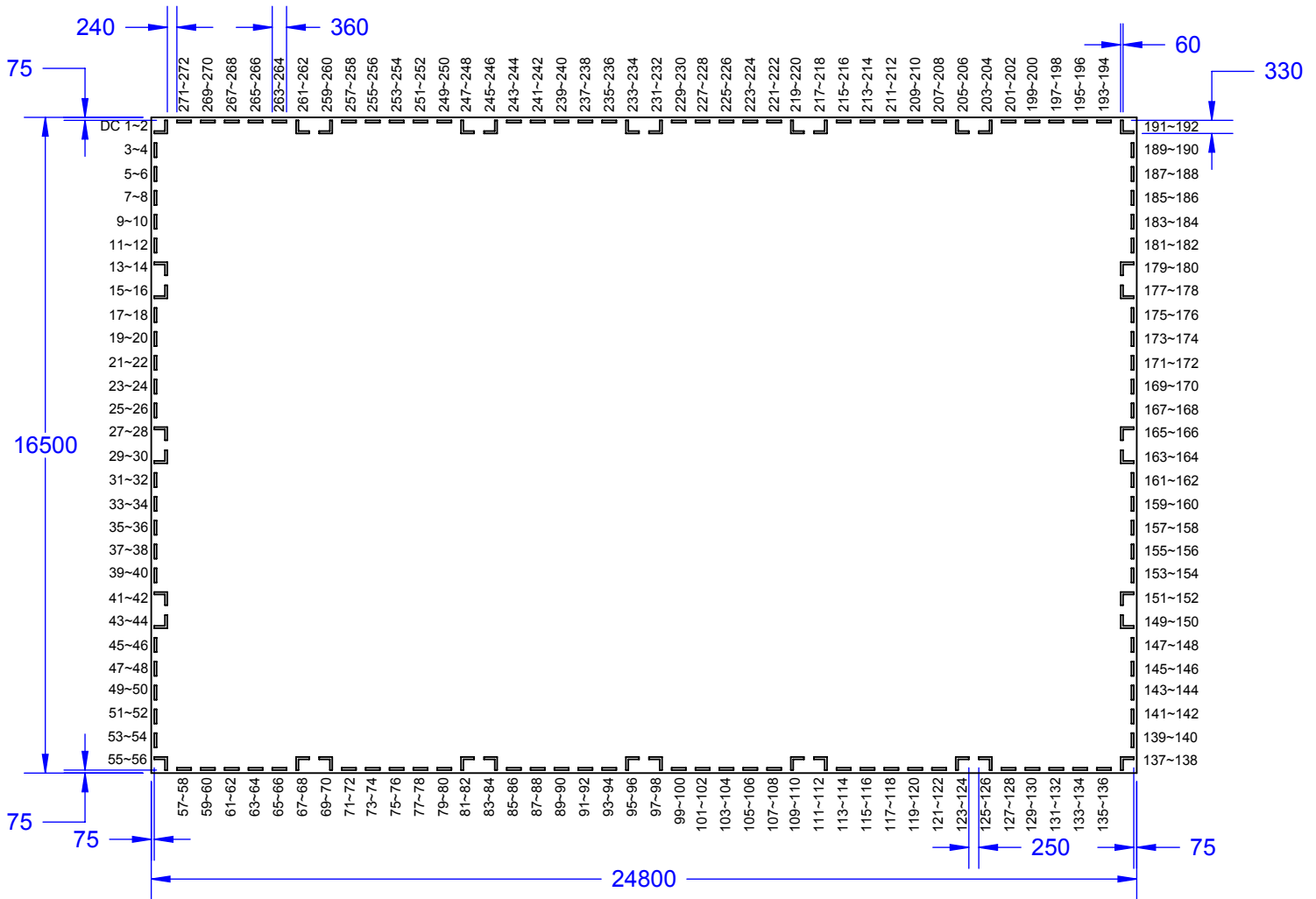
# DAISY CHAIN TEST DIE WIRE BONDABLE SHOWN WITH CENTER PADS



- Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
  2. DIE THICKNESS 250 $\mu$ m ~ 725 $\mu$ m.
  3. METALLIZATION 1.0 $\mu$ m ALUMINUM (Al).
  4. DIE IS WITHOUT PASSIVATION.
  5. WIRE BONDABLE WITH GOLD (Au) WIRE.
  6. DAISY CHAIN PAIRS.

APPROVALS	DATE	<b>TopLine<sup>®</sup></b>			
DRAWN T. Au	04/15/14				
ENG M. Hart	04/15/14	TITLE DAISY CHAIN TEST DIE TD136 16.5 x 25MM			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	154136	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

# PERIMETER PAD TEST DIE DAISY CHAIN SHOWN WITHOUT CENTER PADS FOR CLARITY



SCALE 3:1

DIMENSION IN MICRONS  
1.0mm = 1000µm

- Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
  2. DIE THICKNESS 250µm ~ 725µm.
  3. METALLIZATION 1.0µm ALUMINUM (Al).
  4. DIE IS WITHOUT PASSIVATION.
  5. WIRE BONDABLE WITH GOLD (Au) WIRE.
  6. DAISY CHAIN PAIRS.

APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T.Au	04/15/14				
ENG M. Hart	04/15/14	TITLE DAISY CHAIN TEST DIE TD136 16.5 x 25MM			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	154136	A
CUST		DO NOT SCALE DRAWING			SHEET 2 OF 2
REVISED					